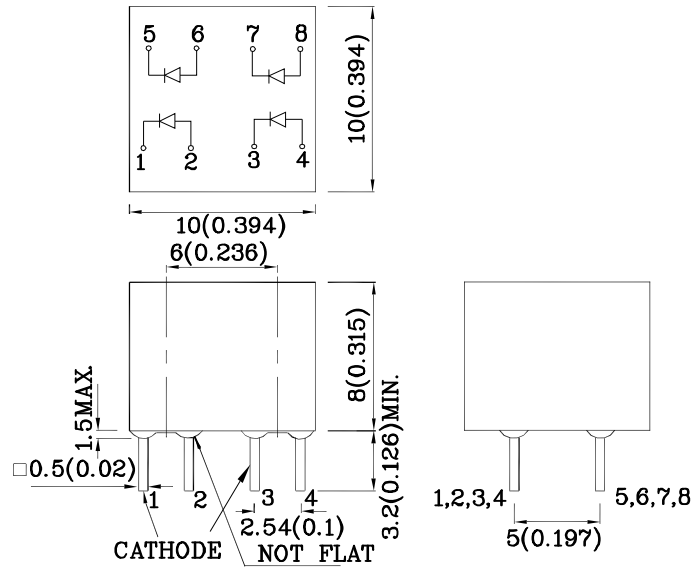


### Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



### Package Schematics



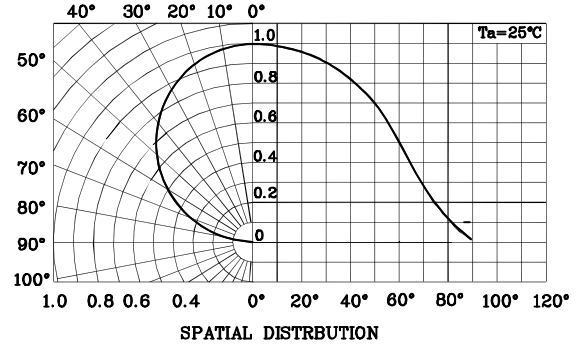
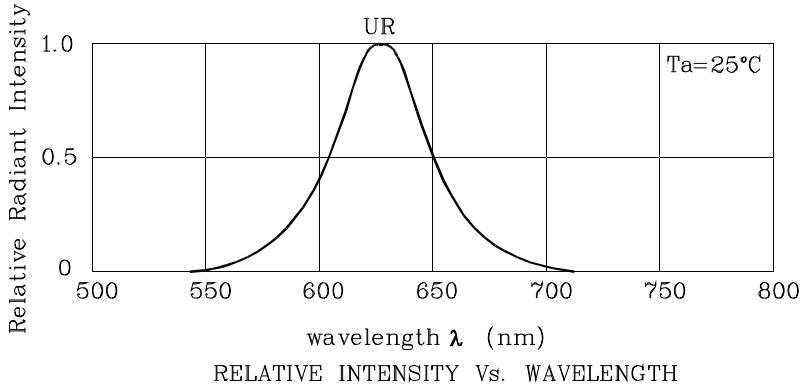
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

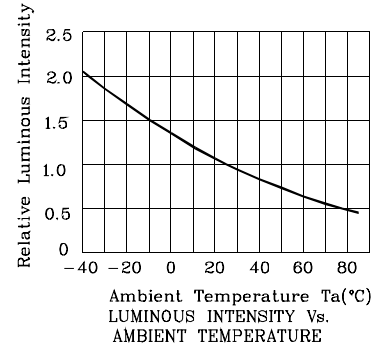
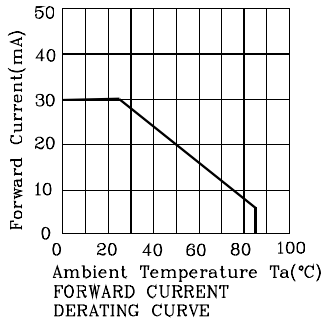
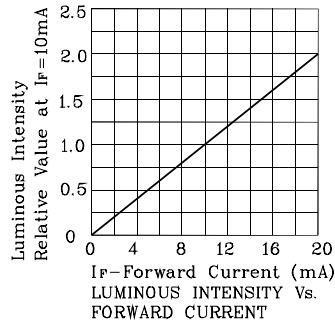
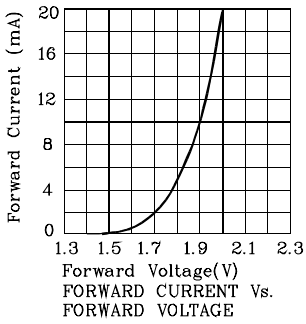
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/GaP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	160	mA
Power Dissipation	$P_D$	75	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	$V_F$	1.9	V
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$	627	nm
Wavelength of Dominant Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=10\text{mA}$ )	$\Delta\lambda$	45	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	15	pF

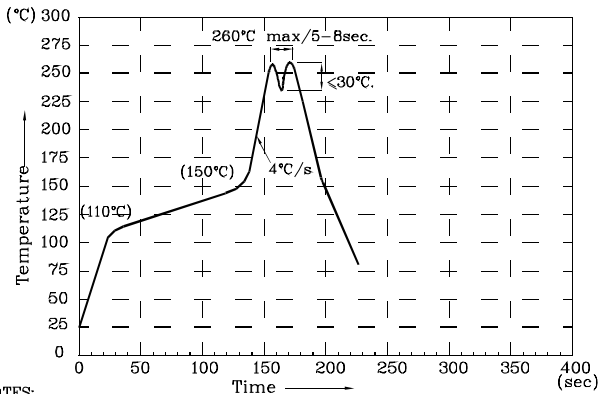
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $I_F=10\text{mA}$ )		Wavelength nm $\lambda_P$	Viewing Angle 2 $\theta$ 1/2
				min.	typ.		
XEUR24D	Red	GaAsP/GaP	Red Diffused	8	14	627	120°



❖ UR



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

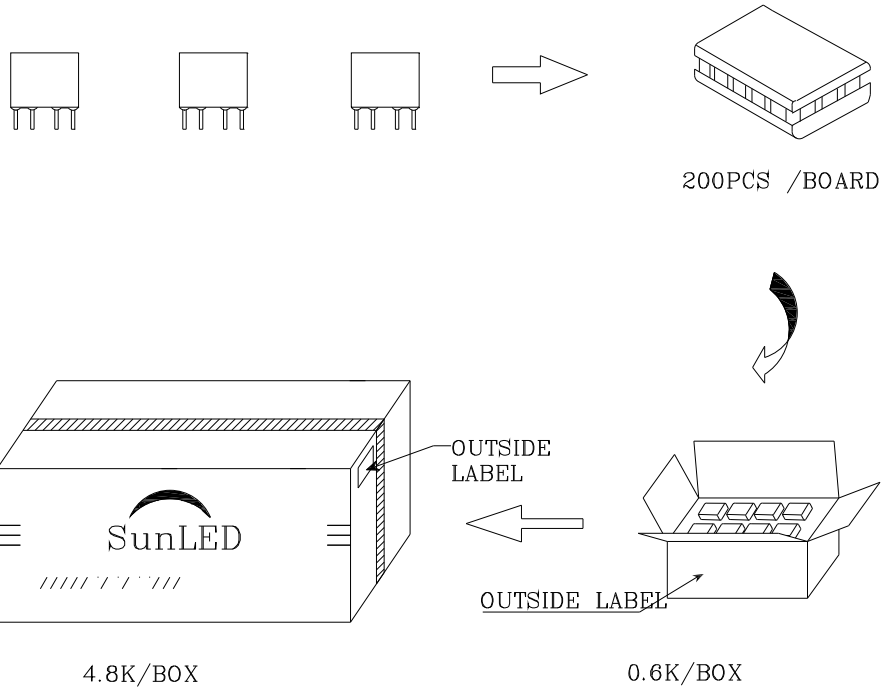

Remarks:



If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="text-align: center;">Q.C.</td> <td style="text-align: center;">Q C</td> </tr> <tr> <td style="text-align: center;">XX</td> <td style="text-align: center;">XX. XXXX</td> </tr> <tr> <td colspan="2" style="text-align: center;">PASSED</td> </tr> </table>	Q.C.	Q C	XX	XX. XXXX	PASSED	
Q.C.	Q C						
XX	XX. XXXX						
PASSED							
P/NO : XE <sub>xx</sub> 24 <sub>x</sub>							
QTY : 200 pcs	CODE: XXX						
S/N : XX							
LOT NO:							
 XXXXXXXXXXXXXXXXXXXXXXXX							
RoHS Compliant							